



SCIENTECH

# Sciencetech Corp(3583:TT)

2024/11/13

# Safe Harbor Statement



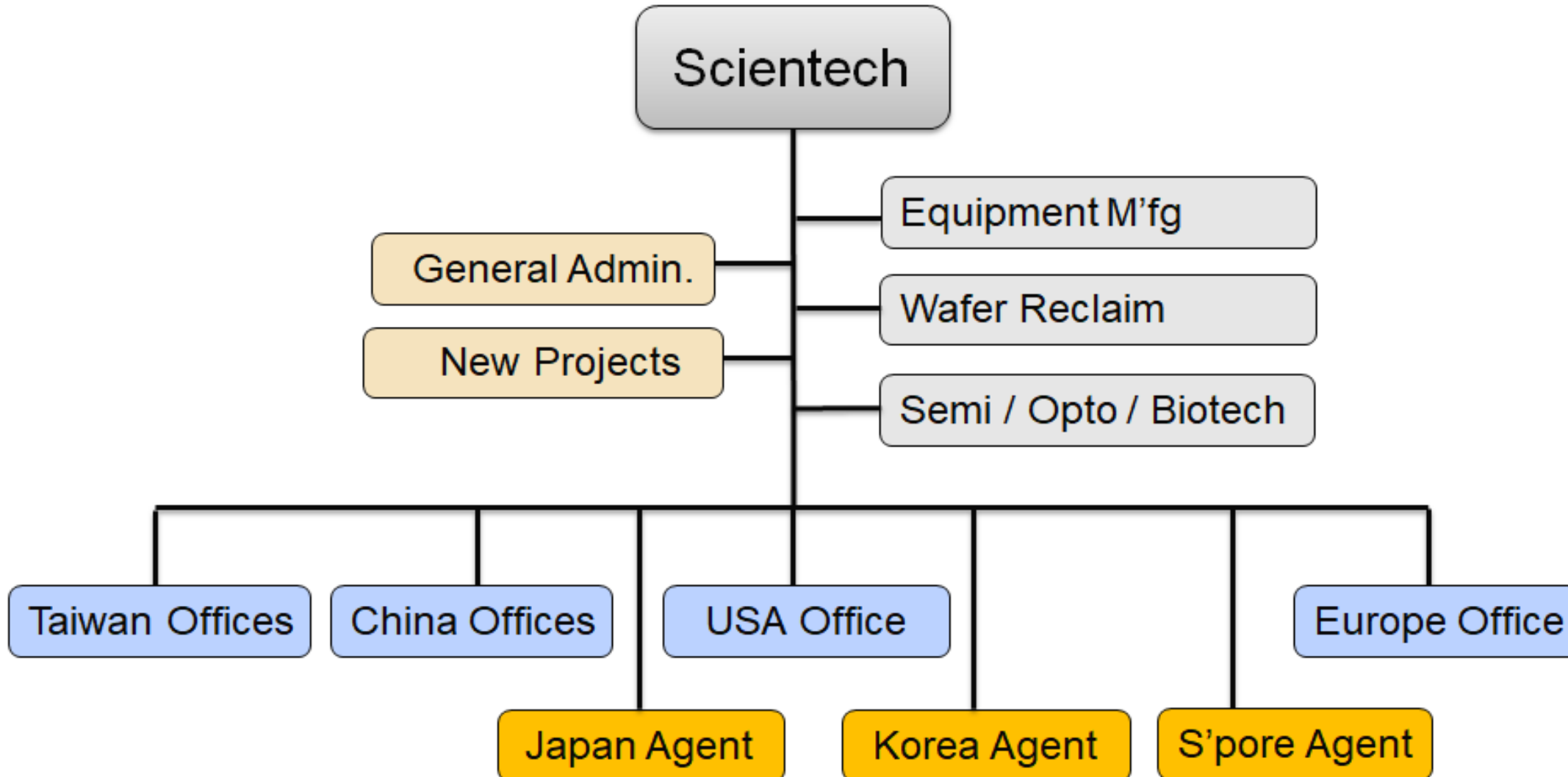
- **This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.**
- **Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.**

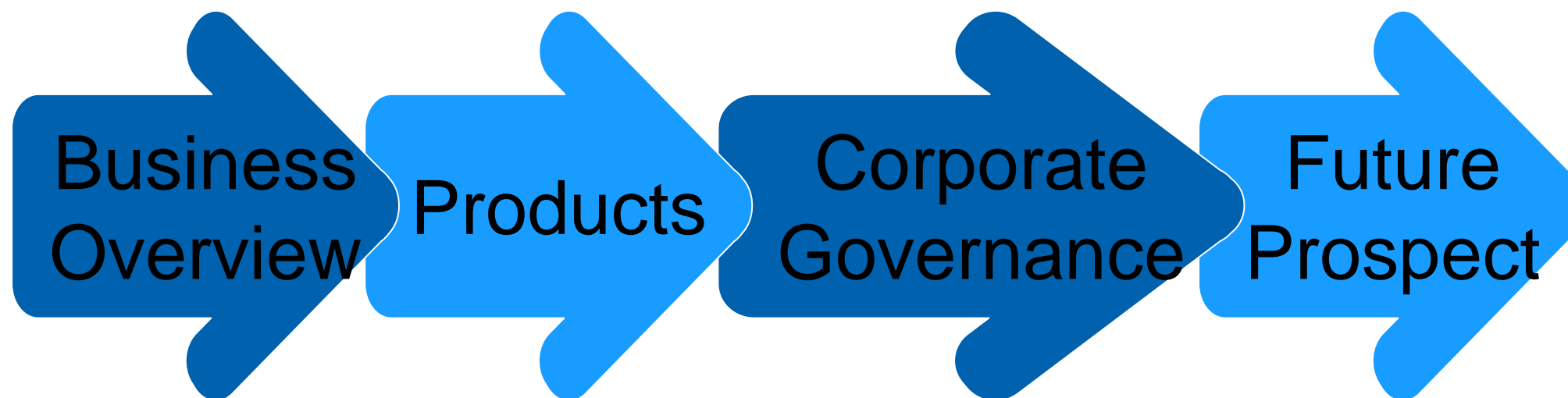
# Sciencetech Corp (3583:TT)



<b>Establishment</b>	1979/10/17
<b>Chairman</b>	H.L. Hsieh
<b>CEO</b>	M.T. Hsu
<b>Capital</b>	NT\$ 803 Million
<b>Revenue(2023)</b>	NT\$ 6,911 Million (Consolidated)
<b>No. Employees</b>	875(Consolidated)
<b>Location</b>	Taiwan : Taipei, Hukou , Hsinchu, Tainan, Kaohsiung Subsidiary Company : China(17 cities including Shanghai) , HK,USA , Europe(Austria) Business Support : Japan,Singapore,South Korea
<b>Products</b>	Equipment Manufacturing 、 Wafer Reclaim 、 Trading(Agent/Distributor)

# Organization





# Business Overview

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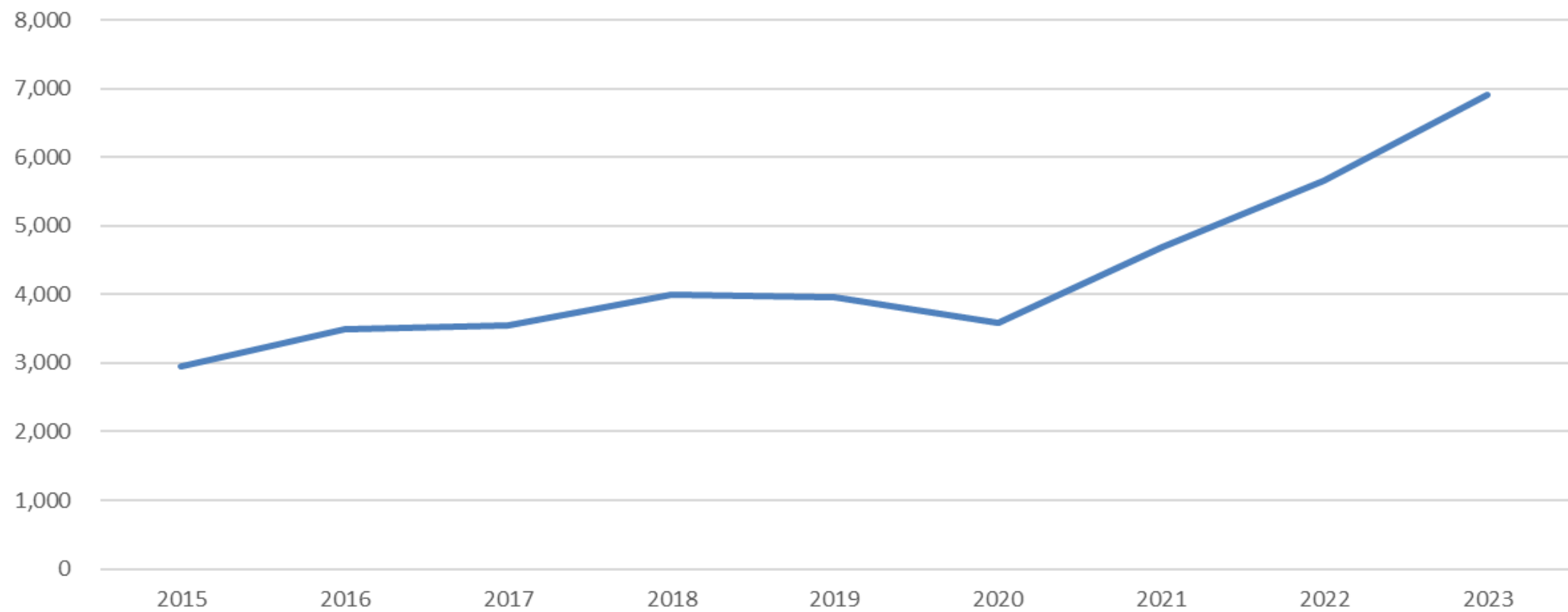
# Income Statement

Units : NT \$ M	2020	2021	2022	2023	2024/Q3
Revenues	3,580	4,684	5,650	6,911	7,117
Gross Profit	1,456	1,667	2,084	2,201	2,163
Operating Expenses	991	1,112	1,374	1,483	1,276
Operating Income	465	555	710	718	887
Income Before Tax	389	524	736	860	897
Net Income	305	420	568	650	677
EPS	<b>3.80</b>	<b>5.23</b>	<b>7.08</b>	<b>8.10</b>	<b><u>8.43</u></b>
Gross Margin	41%	36%	37%	32%	30%
Operating Margin	13%	12%	13%	10%	12%
Income Before Tax Margin	11%	11%	13%	12%	13%

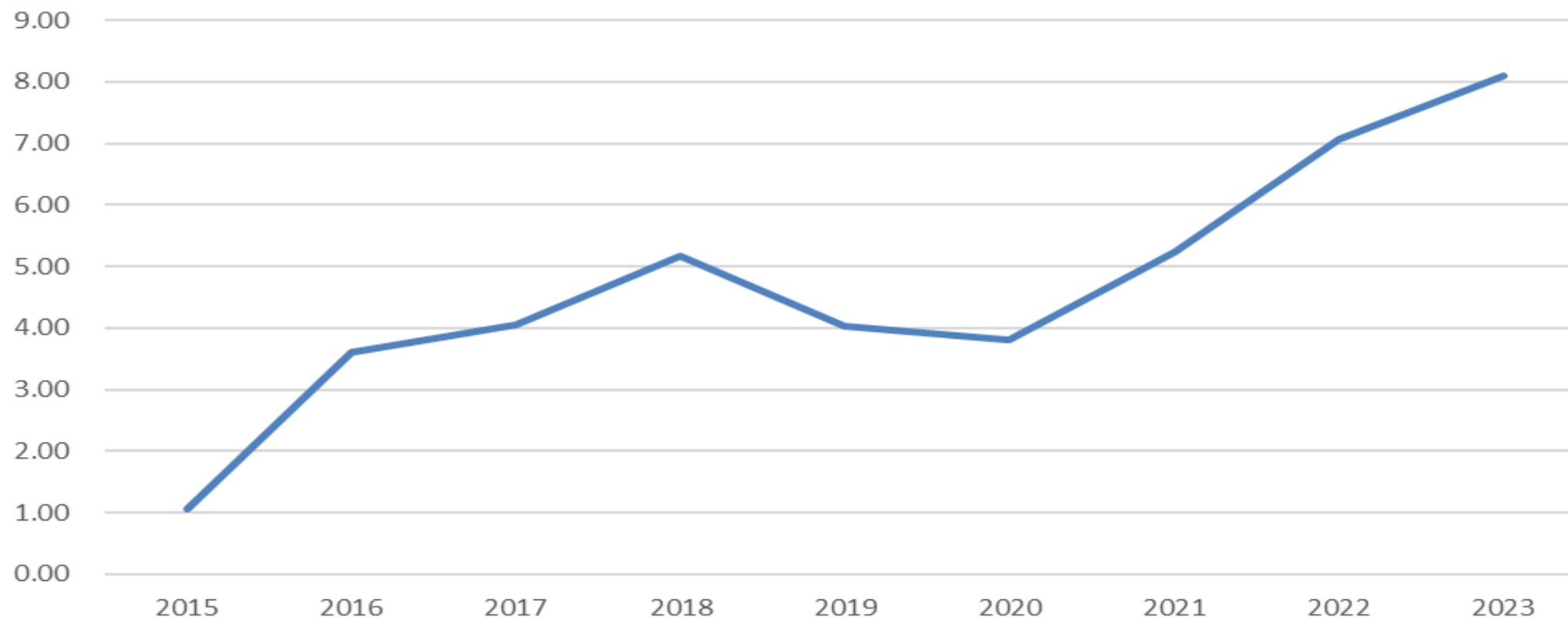
# Revenue



Units NT \$ M	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024/Q3
Revenue	2,942	3,495	3,539	3,988	3,949	3,580	4,684	5,650	6,911	7,117

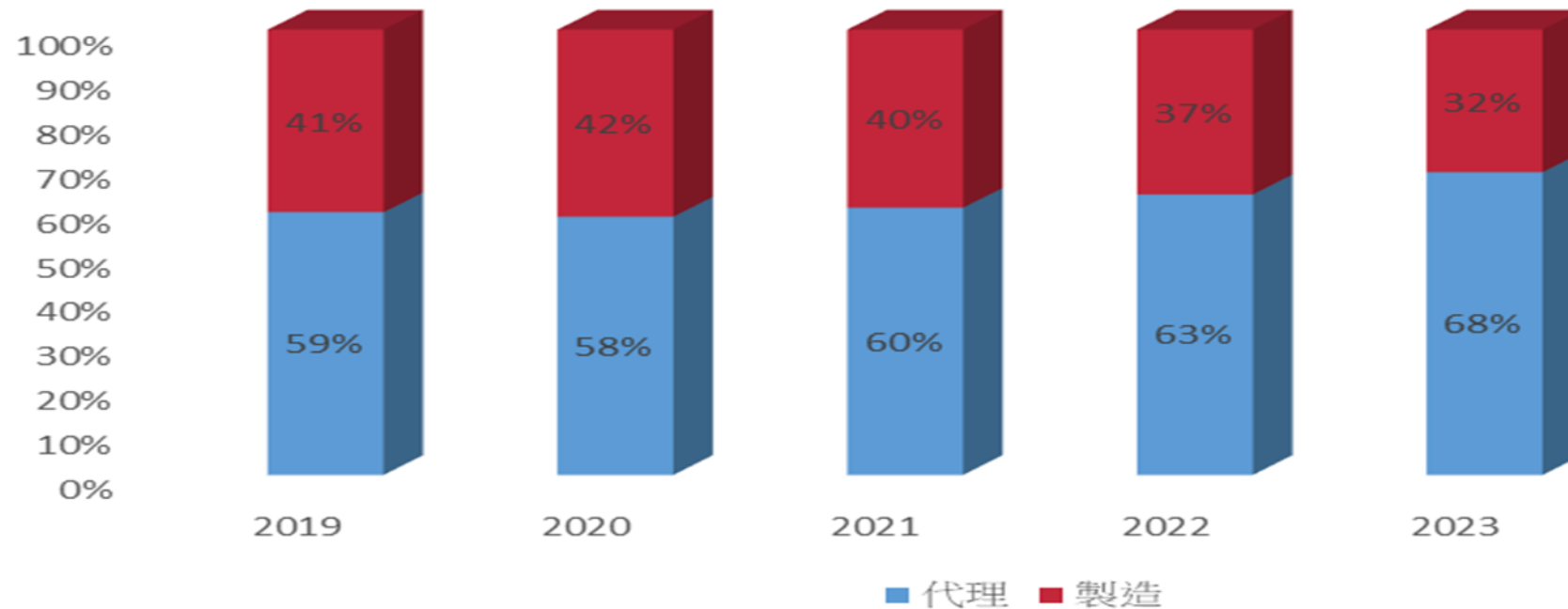


	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024/Q3
EPS	1.06	3.60	4.05	5.16	4.02	3.8	5.23	7.08	8.10	8.43



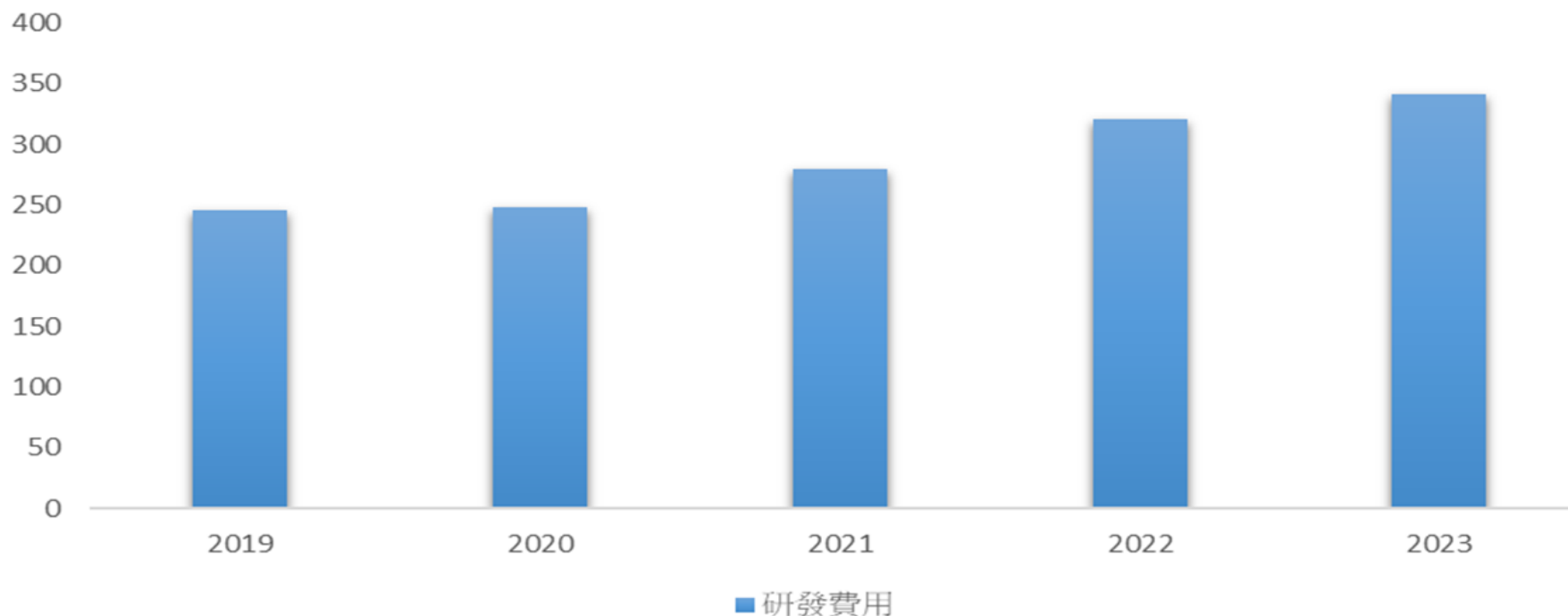
# Products Mix

Units : %	2019	2020	2021	2022	2023	2024/Q3	Gross Margin
Trading	59	58	60	63	68	67	Below Average
Manufacturing	41	42	40	37	32	33	Above Average



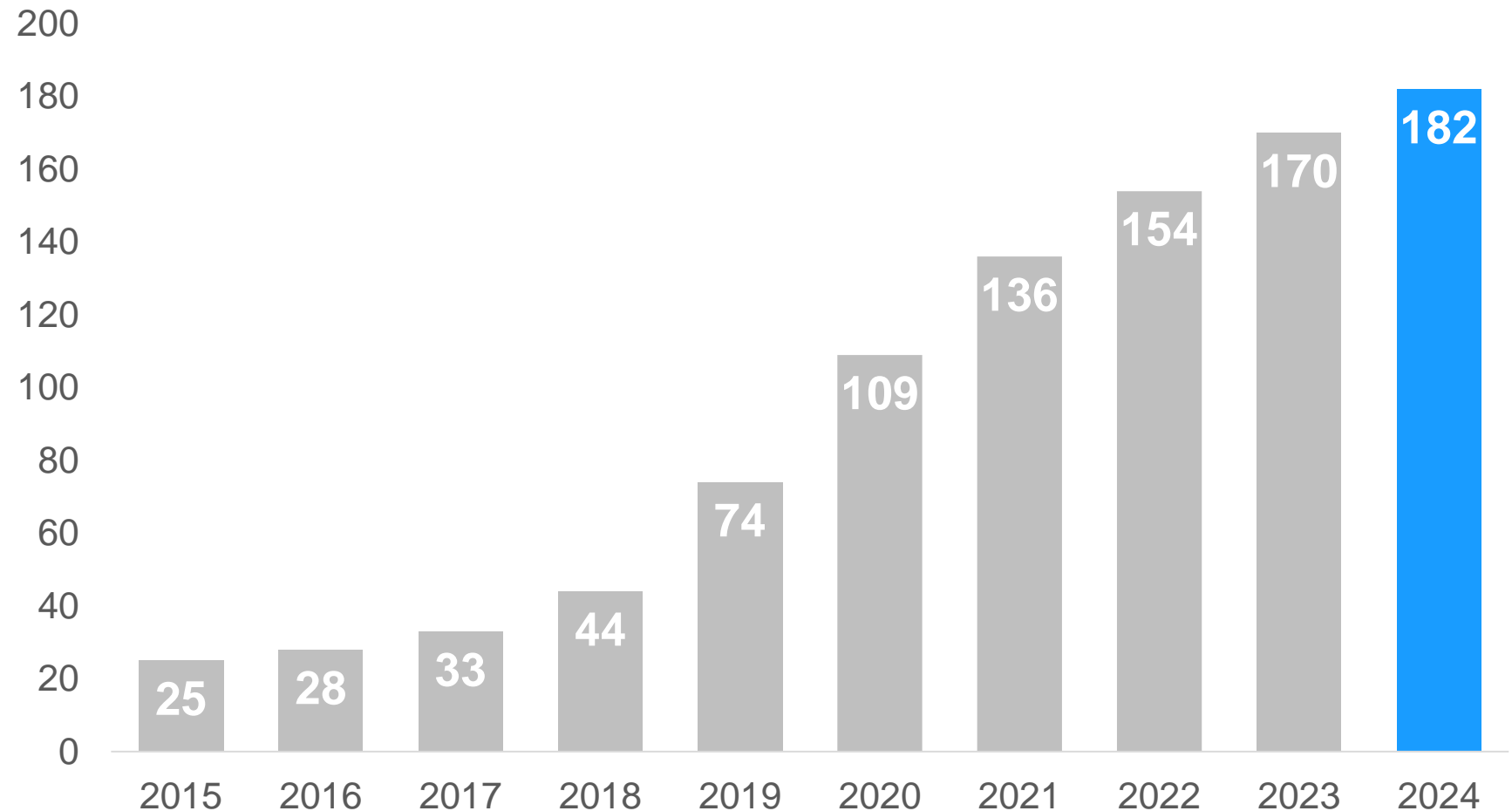
# R&D Expenses

Units NT \$ M	2019	2020	2021	2022	2023	2024/Q3
R&D Expenses	246	248	280	320	341	273
Expenses as % of Revenue	6.2%	6.9%	6.0%	5.7%	4.9%	3.8%
Expenses as % of Manufacturing	15.2%	16.5%	14.9%	15.3%	15.7%	11.5%



# R&D Patents Number

- The cumulative number of patents on file is 182, and 48 applications are pending.



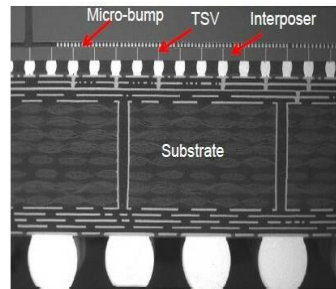
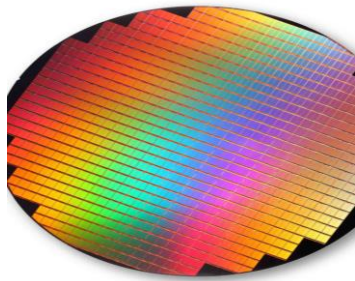
# Products

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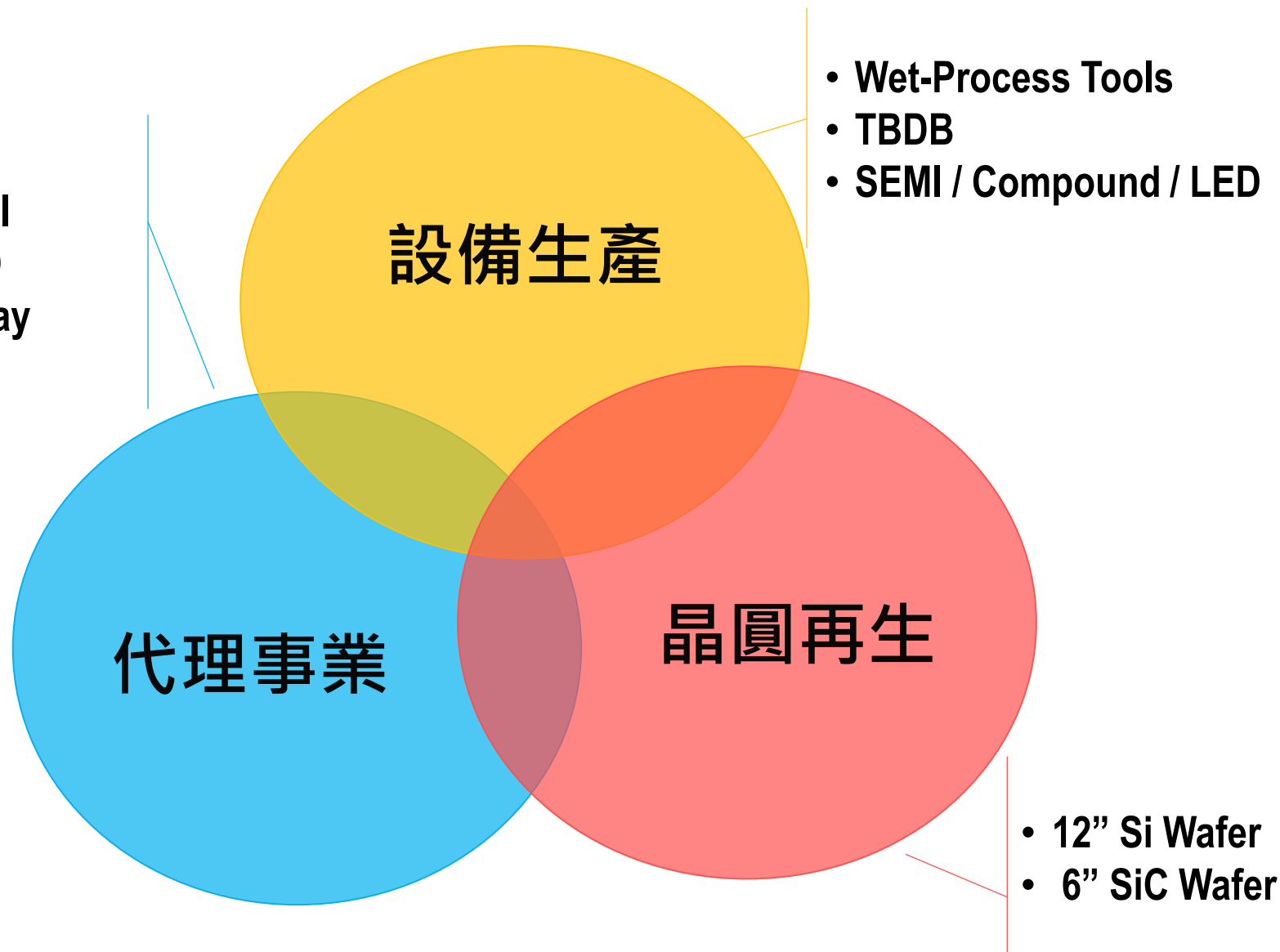


# What We Do

- **Industries which we serve :**
  - **Semiconductor (Front-End and Advanced Packaging)**
  - **Compound Semiconductor**
  - **LED / Mini LED / Micro LED**
  - **Flat Panel Display**
  - **Biotech / Chemistry Analysis / Scientific Instrument,...**



- Semiconductor
- Compound SEMI
- LED / Micro LED
- Flat Panel Display
- Biotech



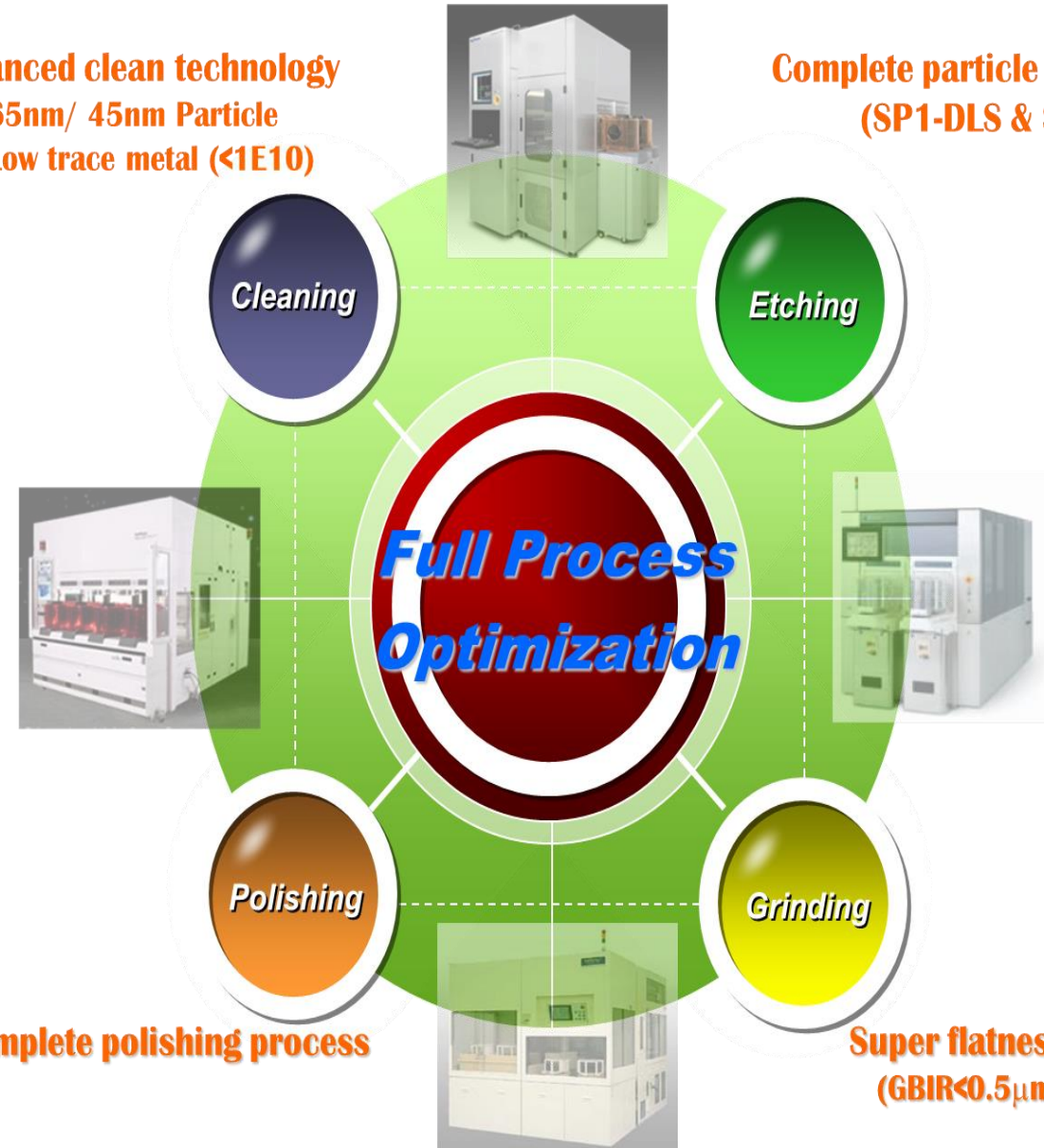
# Wafer Reclaim Service

- **12" Wafer Reclaim**
  - Capacity: 160K/Month
  - Cu and Non-Cu Process
- **SiC Post Slicing Process and Reclaim**
  - Capacity: 0.8K/Month

Advanced clean technology

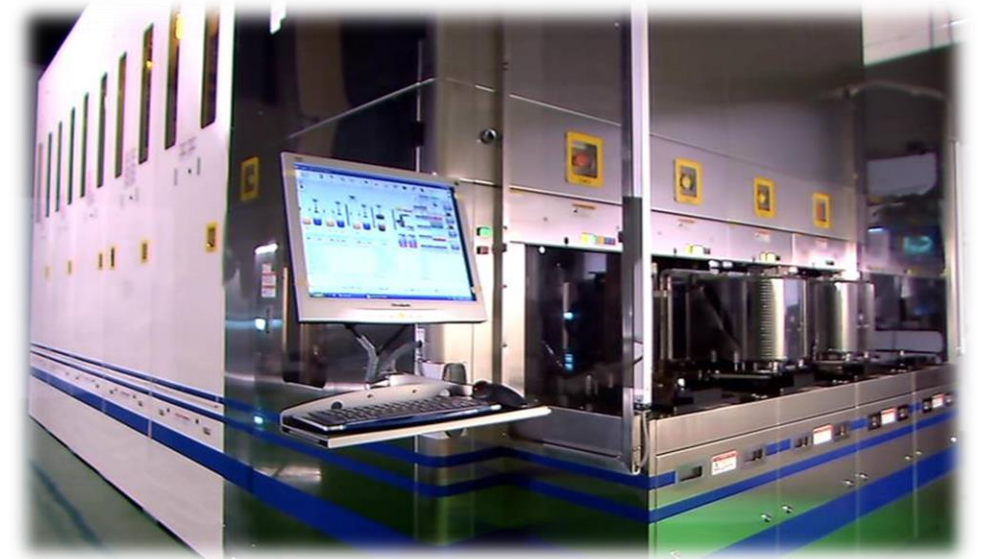
- 65nm/ 45nm Particle
- Low trace metal ( $<1E10$ )

Complete particle inspection  
(SP1-DLS & SP2)



# Wet Process Equipment

- **Wet-Bench / Single-Wafer Wet Process Equipment**
- **Applications :**
  - Advanced Packaging Process
  - Semiconductor Front-End Process
  - Compound Semiconductor
  - Microelectromechanical Systems (MEMS)
  - High-End LED Fully-Automatic Advanced Process

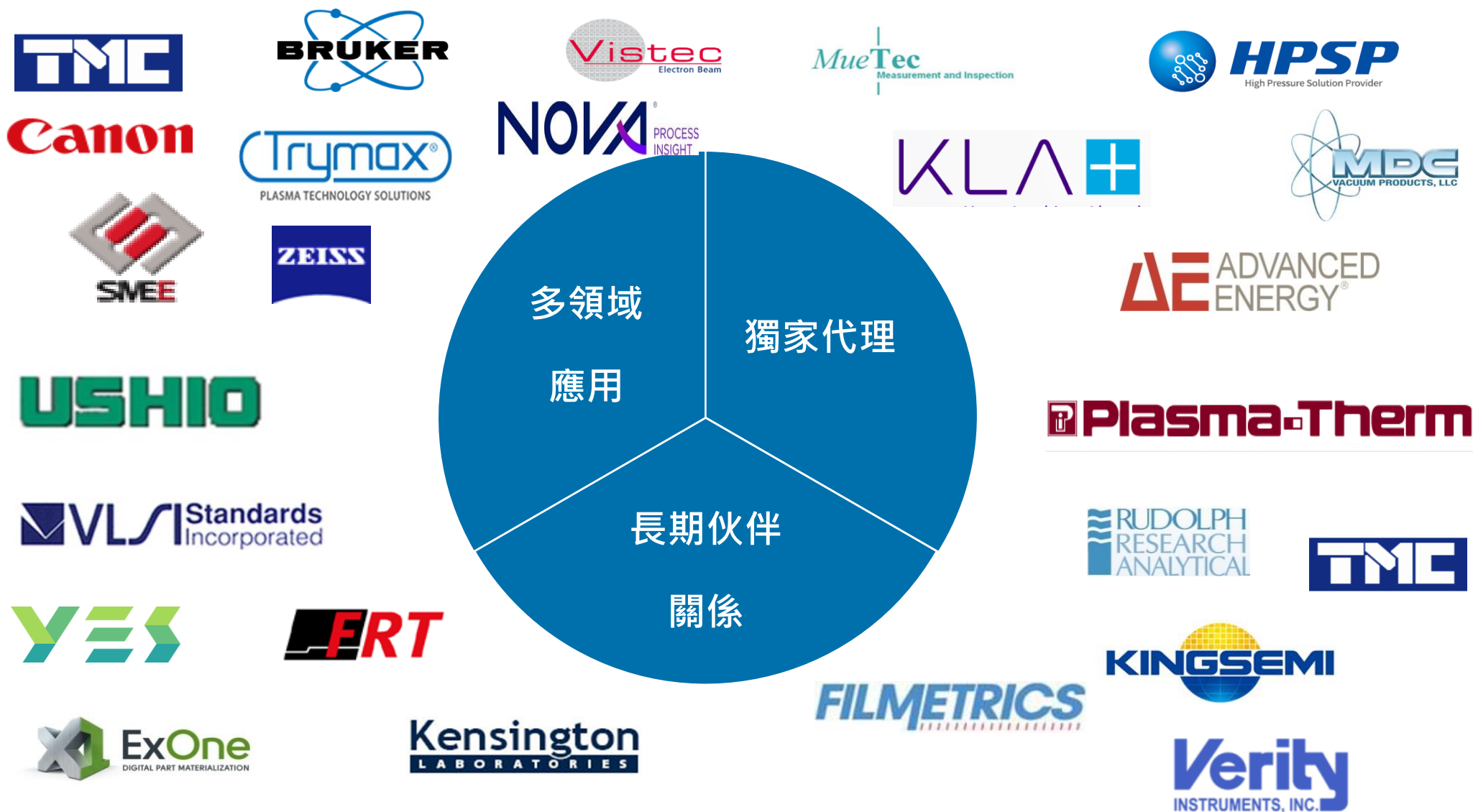


# Temporary Bonding Debonding System

- **Temporary Bonding Debonding System (TBDB)**
- **Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED**
  - Temporary Bonding System
  - Temporary Debonding System
  - Release Layer Formation System
  - Carrier (Glass) Recycling System



# Trading(Agent/Distributor)



# Corporate Governance

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# ISO Certifications

**Initial Certification**  
2014/5/27  
**Valid Date :**  
2020/5/28 ~ 2023/5/27



**Issue 4. Certified since**  
2010/3/24  
**Valid Date :**  
2019/4/30 ~ 2022/4/30



**Issue 3. Certified since**  
2019/4/30  
**Valid Date :**  
2019/4/30 ~ 2022/4/30



**Issue 1. Certified since**  
2019/11/20  
**Valid Date :**  
2019/11/20 ~ 2022/11/19



**Issue 1. Certified since**  
2021/09/29  
**Valid Date :**  
2021/09/29 ~ 2024/09/28



**ISO9001**

**ISO14001**

**ISO45001**

**ISO27001**  
資訊安全

**ISO22301**  
營運持續

## • TIPS-AA級驗證



Taiwan Intellectual Property Management System

### 台灣智慧財產管理規範 (TIPS) 驗證登錄證書

Certificate of Taiwan Intellectual Property Management System

貴公司所建置之智慧財產管理制度，通過台灣智慧財產管理規範 (TIPS) 推行體系之驗證，特此證明。相關登錄事項如下：

- 一、公司名稱：卓新企業股份有限公司
- 二、受評部門：全公司
- 三、受評地址：新竹縣港口鄉中華路16號
- 四、證書編號：TIPS-2019-驗證-008
- 五、有效期限：2021/12/31
- 六、管理標的：☒專利 ☒商標 ☐著作權 ☐營業秘密 ☐積體電路佈局
- 排除適用：無
- 七、驗證類別：☒AA級 ☐A級 (2016年版)

經濟部工業局  
局長 呂正華

### Certificate of Compliance

This is to certify that the Intellectual Property Management System of the following organization has been verified and fulfilled the requirements of TIPS.

- 1. Company Name : Scientech Corporation
- 2. Registered Department : All Company
- 3. Registered Address : No. 16, Jhonghua Rd., Hukou Township, Hsinchu County 30352, Taiwan (R.O.C.)
- 4. Number of Registration : TIPS-2019-cert-008
- 5. Date of Expiration : December 31, 2021
- 6. Items : ☒ Patent ☒ Trademark ☐ Copyright ☐ Trade Secret ☐ Integrated Circuit Layout
- Exclusion : None
- 7. Certification Level : ☒ AA ☐ A (2016)

Director General  
Industrial Development Bureau, MOEA  
Richard Lee

## Sustainability Report Officially Released 2024/08



# Future Prospect

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# Overall Market Direction

- **2024 Global Semiconductor Industry is expected to return to growth trends.**
  - 2023 Production Value is estimated to decrease by 11%, but utilization rates are expected to increase by 16% in 2024, with a further 12.5% increase in 2025
- **2024 Taiwan Semiconductor Industry's production value is estimated to grow by 21.3%, reaching NT\$4.76 trillion, foundry 28% 、Memory/IDM 18% 、IC Packaging 6% 、IC design 15%.**
- **2025 Taiwan Semiconductor Industry's production value is estimated to grow by 15.9%, reaching NT\$5.52 trillion, foundry 18% 、Memory/IDM 15% 、IC design 14%.**
- **12" Semiconductor Advanced Process continues to develop :**
  - Front-end : 5nm 、3nm 、2nm 、1nm
  - Packaging : Advanced packaging technologies such as Fan-Out 、2.5D(CoWos) 、3D(SoIC), ...etc.
- **CoWoS production capacity is expanding rapidly to meet the rising demand for AI chip applications.**
- **Semiconductor AI applications spread from data centers to personal devices.**
- **China's semiconductor expansion is intensifying, with maturing processes leading to increased competition.**
- **Compound SEMI**
  - Due to the decline in smartphone demand, demand for GaAs has slowed down.
  - SiC demand : Gradual increase, with construction slowing down.



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Thank You!

<https://www.scientech.com.tw>